

PATENT

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FEB 2 5 2004

Applicant:	Rajendra D. PENDSE, et al.)	
)	Examiner: Victor V. Yevsikov
Application	n No.: 09/802,443)	
)	Group Art Unit: 2825
Filed:	March 9, 2001)	<u>-</u>
	,)	Date: February 13, 2004
Title:	Flip chip-in-leadframe package and)	
	process)	
		_)	CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on February 13, 2004.

gned Paula Faulk Hurley

COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

Responsive to the Office action mailed August 13, 2003, kindly amend the application as follows:

Amendments to the claims are reflected in the **Listing of Claims** which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.